

ABSTRACT

An interconnect substrate comprising: a first substrate (10) on which a first interconnect pattern (12) is formed, having a mounting region (14) for an electronic chip; and a second substrate (20) on which a second interconnect pattern (22) electrically connected to the first interconnect pattern (12) is formed, having a region (26) to which at least a part of the first substrate (10) is adhered, and a mounting region (24) for an electronic chip.